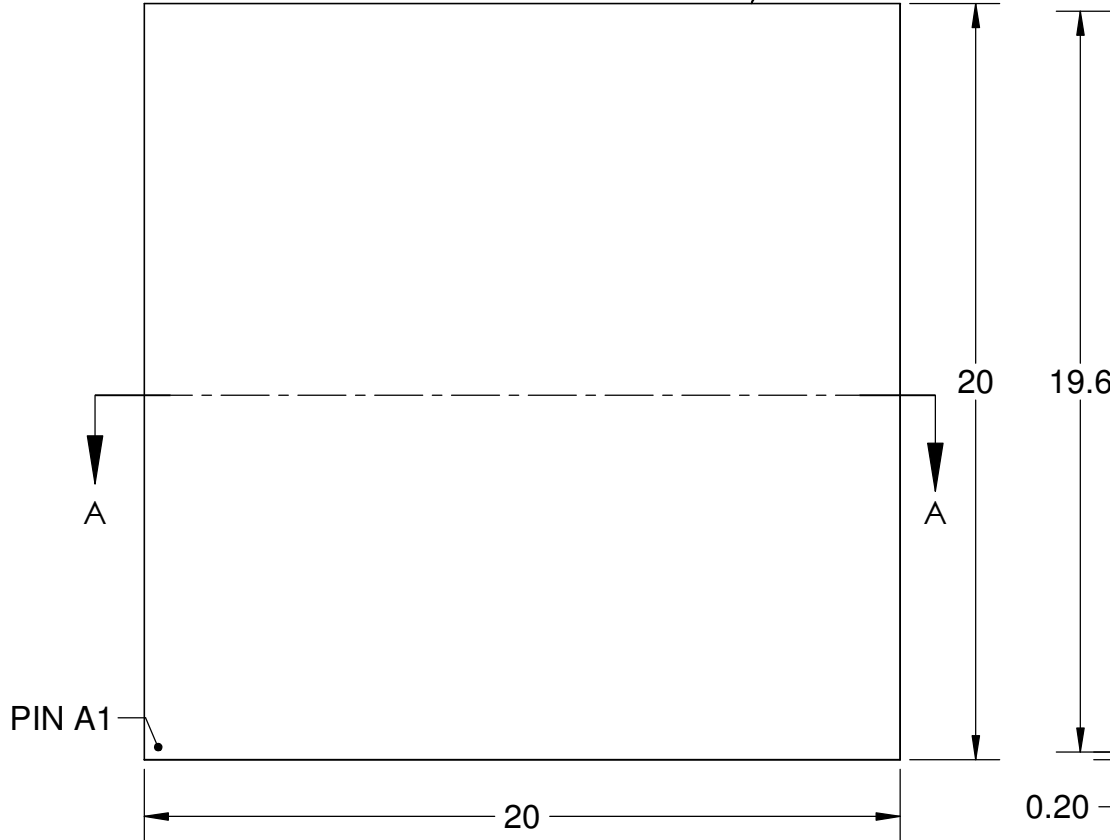
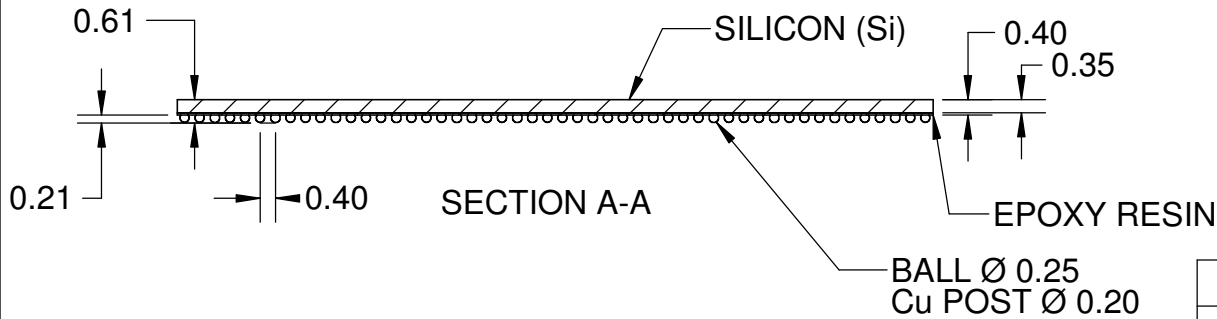
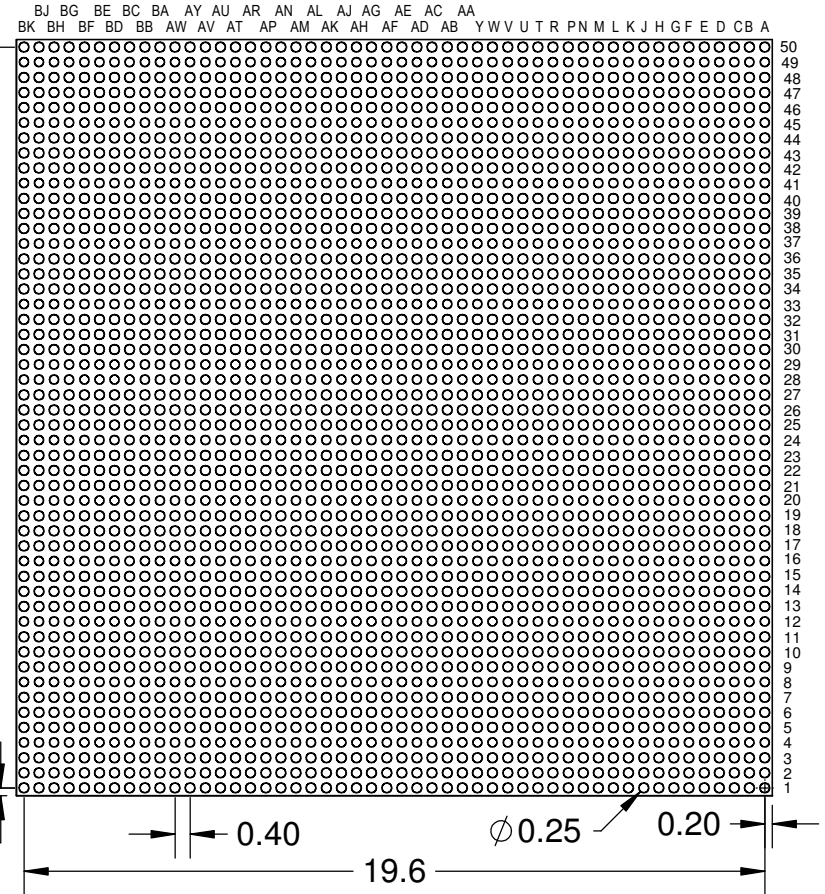


TOP VIEW

SILICON (Si)




BALL VIEW



Notes: (Unless Otherwise Specified).

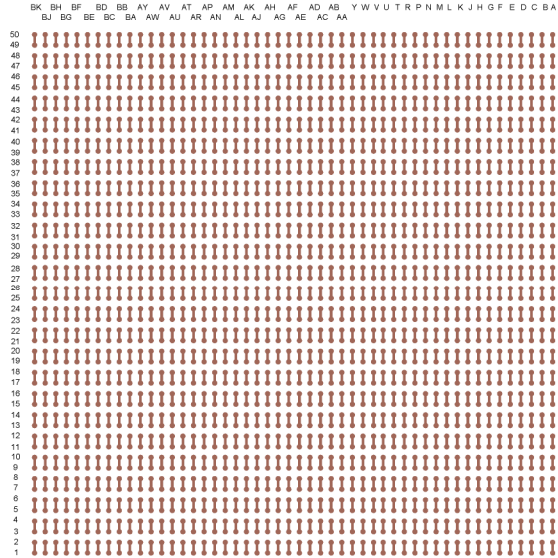
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.20mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP2500T.4C-DC507D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

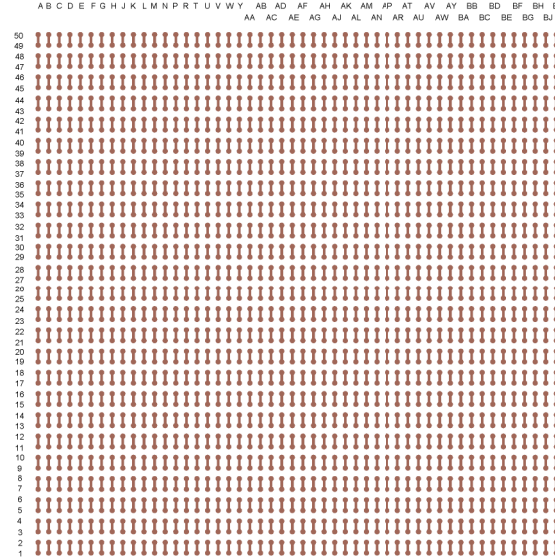
APPROVALS		DATE			
DRAWN	T. Au	02/06/18			
ENG	M. Hart	02/06/18	TITLE		
MFG			WLP2500T.4C-DC507D 2500 ALL P=0.4mm (TEG0408)		
QA			SCALE	SIZE	DRAWING NO.
CUST				A	545070
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 2

DAISY CHAIN PATTERN

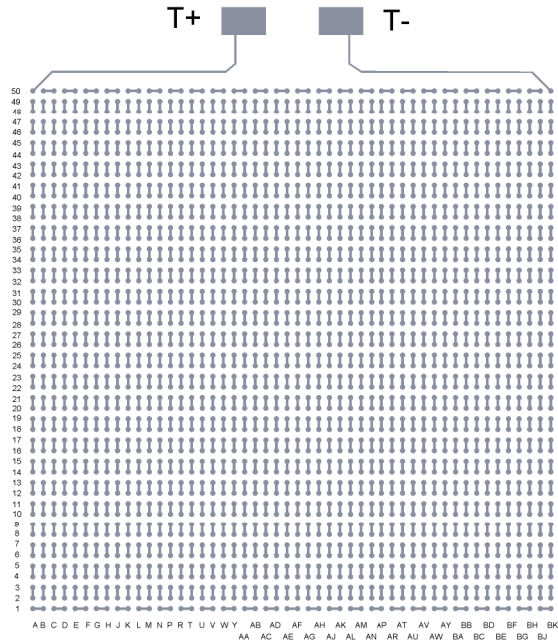
BALL VIEW



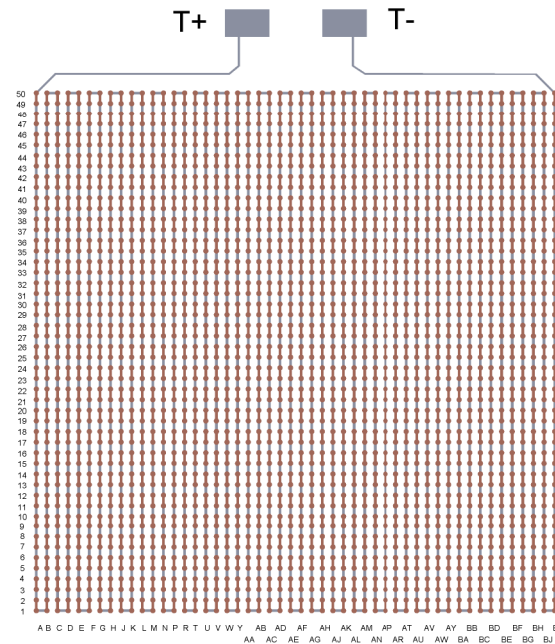
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.20mm (7.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine®			
TITLE		WLP2500T.4C-DC507D 2500 ALL P=0.4mm (TEG0408)	
SCALE	SIZE	DRAWING NO.	REV
	A	545070	A
DO NOT SCALE DRAWING			SHEET 2 OF 2